Environmental Management and Materials Information

Part Number: DS2761BX-025
Package Type: Flip Chip
Lead-Free Qualified: No

Wafer Size	Device Structure	Die Size (mil^2)	Die Size (cm^2)	UBM Size (µm)	Bump Area (cm^2)	No. of Bumps
200mm	High-lead flip chip	10476	0.06760	200	0.000003141	14

BCB No. of Layers	BCB Final Thickness (µm)	BCB Density (gm/cc)	BCB Weight (grams)	RDL Ti Weight (gram)	RDL Al Weight (gram)	UBM Cr Weight (gram)
2	5	0.95	0.000064200	0.00000152	0.0000137	0

UBM Ti Weight (gram)	UBM W Weight (gram)	UBM Ni Weight (gram)	UBM Cu Weight (gram)	Ball/Bump Pb Weight (gram)	Ball/Bump Sn Weight (gram)	Silicon Chip Weight (grams)
0.0000008390	0.00003230	0.000012400	0.000020800	0.0001990	0.000006750	0.006790

Net Weights - Total Product 0.007141509 grams				
CAS#'s	7440-32-6	7429-90-5	7758-97-6	7440-33-7
BCB	Titanium (Ti)	Alumimum (Al)	Chromium (Cr)	Tungsten (W)
0.000064200	0.0000023590	0.0000137	0	0.00003230

7440-02-0	7440-50-8	7439-92-1	7440-31-5	7440-21-3
Nickel (Ni)	Copper (Cu)	Lead (Pb)	Tin (Sn)	Silicon (Si)
0.000012400	0.000020800	0.0001990	0.000006750	0.006790

Weight in Percent - Total Product 100%				
CAS#'s	7440-32-6	7429-90-5	7758-97-6	7440-33-7
BCB	Titanium (Ti)	Alumimum (Al)	Chromium (Cr)	Tungsten (W)
0.90%	0.03%	0.19%	0.00%	0.45%

7440-02-0	7440-50-8	7439-92-1	7440-31-5	7440-21-3
Nickel (Ni)	Copper (Cu)	Lead (Pb)	Tin (Sn)	Silicon (Si)
0.17%	0.29%	2.79%	0.09%	95.08%

Definitions
BCB – Benzocyclobutene
UBM – Under-Bump Metal
RDL – Redistribution Layer